J-BHI Special Issue on
"Internet of Medical Things for Health Engineering"

Recently, due to the unmet need to address the grand challenges in preventive medicine and the advances in information and computer technologies, the medical and health care are making a paradigm shift from hospital-centred to patient-centred, and from disease-focus to health-focus. With the increasing demand for lower-cost, more convenient, and smarter healthcare solutions, extensive research has been dedicated to the development of novel Internet of Medical Things (IoMT) devices, circuits, systems, platforms, and their applications for health engineering, which are leading to a new and promising healthcare strategy transform. In IoMT, the enabling technologies such as smart biosensors and bioelectronics, wearable and flexible devices, lab-on-a-chip integration, big data collection, analytics, mining and fusion, communication, as well as proactive health management are all paving the way for this new strategy.

Considering this situation, this special issue is dedicated to the state-of-the-art health engineering related topics and emphasizes the interdisciplinary bioelectronics and bioinformatics-related topics for health informatics and engineering. Through a collection of original and invited papers, this issue aims to promote the awareness of IoMT technologies in the community of healthcare, and encourage the research collaboration across the fields to address the critical and urgent healthcare concerns.

Topics include but are not limited to:
- Multimodal healthcare sensors
- Wearable and implantable sensors
- Mobile and lab-on-a-chip healthcare microsystems
- Point-of-care healthcare instrumentation
- Unobtrusive biosensing
- Home-care robotics
- Bioinformatics for healthcare engineering
- Medical data mining and big-data analytics
- Machine learning/deep learning for healthcare
- Biomedical Signal and Image Processing of IoMT
- IoMT architecture, implementation and application

Guest Editors
Jinhong Guo
School of Information and Communication,
University of Electronic Science and Technology of China
guojinhong@uestc.edu.cn

Xiwei Huang
College of Electronics and Information, Hangzhou Dianzi University, China
huangXiwei@hdu.edu.cn

Santosh Pandey
School of Electrical & Computer Engineering, Iowa State University
pandey@iastate.edu

Yuan-Ting Zhang
Department of Mechanical and Biomedical Engineering
City University of Hong Kong
yt.zhang@cityu.edu.hk

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